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TITLE : SINGLE-LAYER MOLDED PRODUCT

ABSTRACT : PROBLEM TO BE SOLVED: To obtain a single-layer molded product excellent in appearance and further flexibility, gas barrier properties, mechanical strength, impact resistance and heat bonding properties to a thermoplastic resin by compounding an ethylene-vinyl alcohol copolymer(EVOH) with a polyamide resin, an olefin-unsaturated carboxylic acid copolymer or its metal salt and the thermoplastic resin and molding the resultant composition.

SOLUTION: This single-layer molded product comprises (A) an EVOH, (B) a polyamide resin, (C) an olefin-unsaturated carboxylic acid copolymer or its metal salt and (D) a thermoplastic resin having ≤ 11 solubility parameter (calculated from the Fedors equation) other than the resin. The single-layer molded product is obtained by compounding the components so that the compounding weight ratio satisfies the following formulae (I) to (IV): (I) $0.6 \leq W(A+D)/W(T) \leq 0.995$, (II) $0.005 \leq W(B+C)/W(T) \leq 0.4$, (III) $0.5 \leq W(D)/W(A+D) \leq 0.99$ and (IV) $0.02 \leq W(B)/W(B+C) \leq 0.98$ [W(A+D) is the total weight of the components A and D in the composition; W(B) is the weight of the component B in the composition; W(B+C) is the total weight of the components B and C in the composition; W(D) is the weight of the component D in the composition; W(T) is the total weight of the composition] and then molding the resultant composition.

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